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FAN3989

USB/Charger Detection Device with Load Switch

Features

- Charger/USB Detection Device with Load Switch
- Charger/USB Device Detection Flag
- Over/Under-Voltage Detection Flag
- Load Switch Output, Up to 1.5A Charge Current
- V_{BUS} Supply: 2.7V to 20V
- C_{ON} : 1.5pF
- Package: 8-Lead MLP

Applications

- Mobile Phones
- Handheld Devices

Related Resources

- [AN-5067 — PCB Land Pattern Design and Surface Mount Guidelines for MLP Packages](#)

Description

The FAN3989 is a USB connection monitoring device used to determine if a standard USB device is connected or a battery-charging device is connected.

The FAN3989 sets the FLAG1 pin to logic HIGH or LOW as an indicator to the system controller that a standard USB device or a charger is connected to the USB port. The FAN3989 also monitors the V_{BUS} for over- or under-voltage conditions. The FLAG2 pin is set LOW if V_{BUS} is less than 3.3V or greater than 6.0V. The internal load switch control pin is set HIGH if V_{BUS} is less than 3.3V or greater than 6.0V, turning off the PMOS switch.

The FAN3989 is available in a very small 8-lead MLP package suitable for small board space applications, like mobile phones.

Ordering Information

Part Number	Operating Temperature Range	Package	Packing Method	Quantity
FAN3989MLP8X	-40°C to +85°C	8-Lead Molded Leadless Package (MLP)	Reel	3000

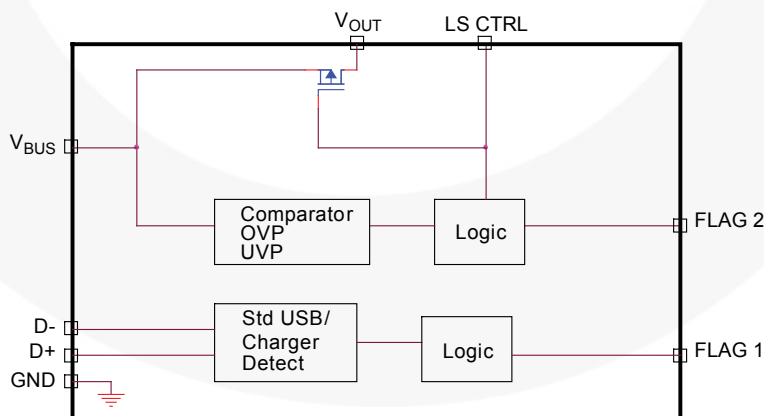


Figure 1. Block Diagram

Pin Configuration

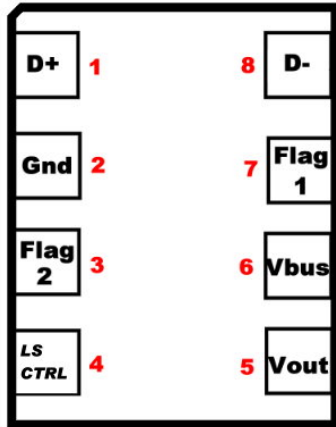


Figure 2. Pin Configuration (Top View)

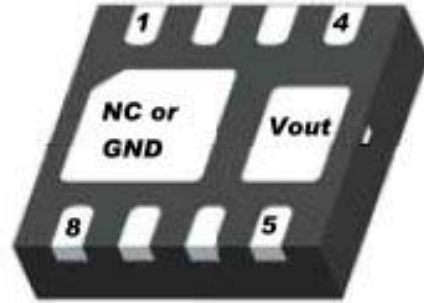


Figure 3. Pin Configuration (Bottom View)

Pin Definitions

Pin#	Name	Type	Description
1	D+	Input	USB Data Input
2	GND	Input	Device Ground
3	Flag2	Output	Over-/Under-Voltage Flag Output
4	LSCTRL	Output	PMOS Switch Control – Pull-Up Connection to V_{BUS}
5	V_{OUT}	Output	Voltage Out – Connection also on Package DAP (see <i>PCB Layout Guideline section</i>)
6	V_{BUS}	Input	Power Input from Charger, USB Device, or Handheld Battery
7	Flag1	Output	Charger / Standard USB Device Detect Flag
8	D-	Input	USB Data Input

Truth Table

Connection State	V_{BUS}	D-	D+	FLAG1	FLAG2	LS CTRL	Description
STD USB Device	0V	R to GND	R to VDD	LOW	LOW	HIGH	Load switch open
STD USB Device	5V	R to GND	R to VDD	LOW	HIGH	LOW	Load switch closed
USB Charger	5V	Short to D+	Short to D-	HIGH	HIGH	LOW	Normal state, load switch closed
V_{BUS} GT 6V	GT 6V	Short to D+	Short to D-	HIGH	LOW	HIGH	Load switch open
V_{BUS} LT 3.3V	LT 3.3V	Short to D+	Short to D-	HIGH	LOW	HIGH	Load switch open
PC Charger	5V	Open	Open	LOW	HIGH	LOW	Load switch closed

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit
V_S	DC Supply Voltage	-0.3	20.0	V
V_{IO}	Analog and Digital I/O	-0.3	$V_{CC}+0.3$	V

Reliability Information

Symbol	Parameter	Min.	Typ.	Max.	Unit
T_J	Junction Temperature			+150	°C
T_{STG}	Storage Temperature Range	-65		+150	°C
Θ_{JA}	Thermal Resistance, JEDEC Standard, Multilayer Test Boards, Still Air		41		°C/W

Electrostatic Discharge Information

Symbol	Parameter	Max.	Unit
ESD	Human Body Model, JESD22-A114	3	kV
	Charged Device Model, JESD22-C101	1	

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Typ.	Max.	Unit
T_A	Operating Temperature Range	-40		+85	°C
V_{CC}	Supply Voltage Range	2.7	5.0	20.0	V

DC Electrical Characteristics

$T_A = 25^\circ\text{C}$, $V_{CC} = 5.0\text{V}$, unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
Supply						
V_S	Supply Voltage Range	V_S Range	2.7	5.0	20.0	V
I_{CC}	Quiescent Supply Current	$V_S = +5.0\text{V}$, D+ D- Shorted		1.2	2.0	mA
t_{SUPPLY}	Power-Up Stabilization Time	$V_S = +5.0\text{V}$, D+ D- Shorted		10		ms
Input Characteristics						
C_{D+}	Input Capacitance			1.5	2.0	pF
C_{D-}	Input Capacitance			1.5	2.0	pF
$I_{off\ D+}$	Off Leakage Current	$V_{BUS} = 0\text{V}$ or 5V V_{IN} on D+ = 5V		1		μA
$I_{off\ D-}$	Off Leakage Current	$V_{BUS} = 0\text{V}$ or 5V V_{IN} on D- = 5V		1		μA
Output Characteristics						
OV_{DETECT}	Over-Voltage Threshold Detect	$V_S = +5.0\text{V}$, Flag2 = LOW	5.8	6.2	6.5	V
OV_{HYST}	Over-Voltage Hysteresis	Voltage Sweep through Upper and Lower Trip Points		100		mV
UV_{DETECT}	Under-Voltage Threshold Detect	$V_S = +5.0\text{V}$, Flag2 = LOW	3.0	3.3	3.6	V
UV_{HYST}	Under-Voltage Hysteresis	Voltage Sweep through Upper and Lower Trip Points		100		mV
$V_{OH\ FLAG1/FLAG2}$	Minimum HIGH Output Voltage	$V_S = +5.0\text{V}$, $I_{OH} = -20\mu\text{A}$	2.4			V
$V_{OL\ FLAG1/FLAG2}$	Maximum LOW Output Voltage	$V_S = +5.0\text{V}$, $I_{OL} = 20\mu\text{A}$			0.3	V
$V_{OL\ LS_CTRL}$	Maximum LOW Output Voltage	$V_S = +5.0\text{V}$, $I_{OL} = 100\mu\text{A}$			0.3	V
VB_{DSS}	Drain Source Breakdown Voltage	$V_{GS} = 0\text{V}$, $I_D = -250\mu\text{A}$	-20			V
R_{DSON}	Static Drain-Source On Resistance	$V_{GS} = -5.0\text{V}$, $I_P = 1\text{A}$		186		m Ω
C_{iss}	Input Capacitance	$V_{DS} = -10\text{V}$, $V_{GS} = 0\text{V}$, $f = 1.0\text{MHz}$		330		pF
C_{oss}	Output Capacitance			80		pF
$t_{d(on)}$	PMOS Turn-On Delay Time	$V_{DD} = -5\text{V}$, $I_P = -0.5\text{A}$,		5		μs
$t_{d(off)}$	PMOS Turn-Off Delay Time	$V_{GS} = -4.5\text{V}$, $R_{GEN} = 6\Omega$		14		μs

Typical Performance Characteristics

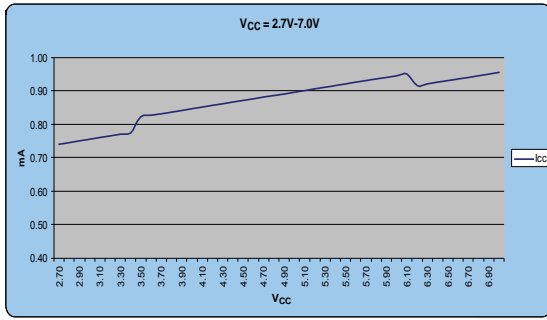


Figure 4. I_{CC} vs. V_{CC} (2.7V-7.0V) No Load

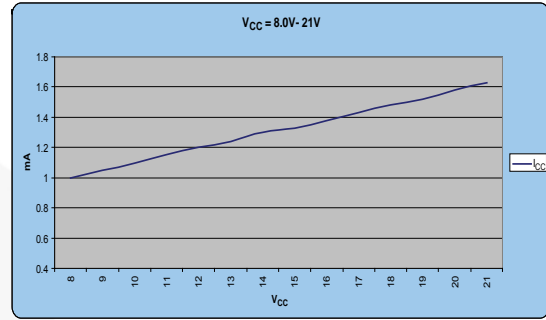


Figure 5. I_{CC} vs. V_{CC} (8.0V-21V) No Load

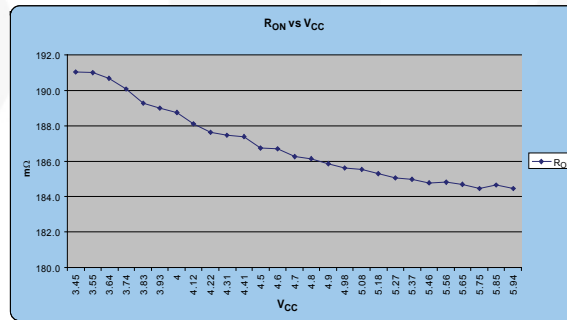


Figure 6. R_{ON} vs. V_{CC} (10Ω Load)

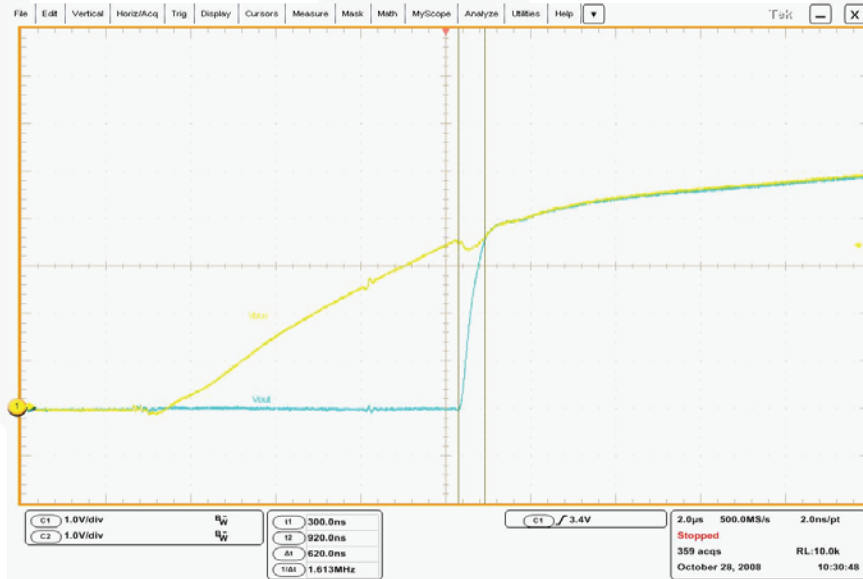


Figure 7. Turn-On Time

Typical Performance Characteristics (Continued)

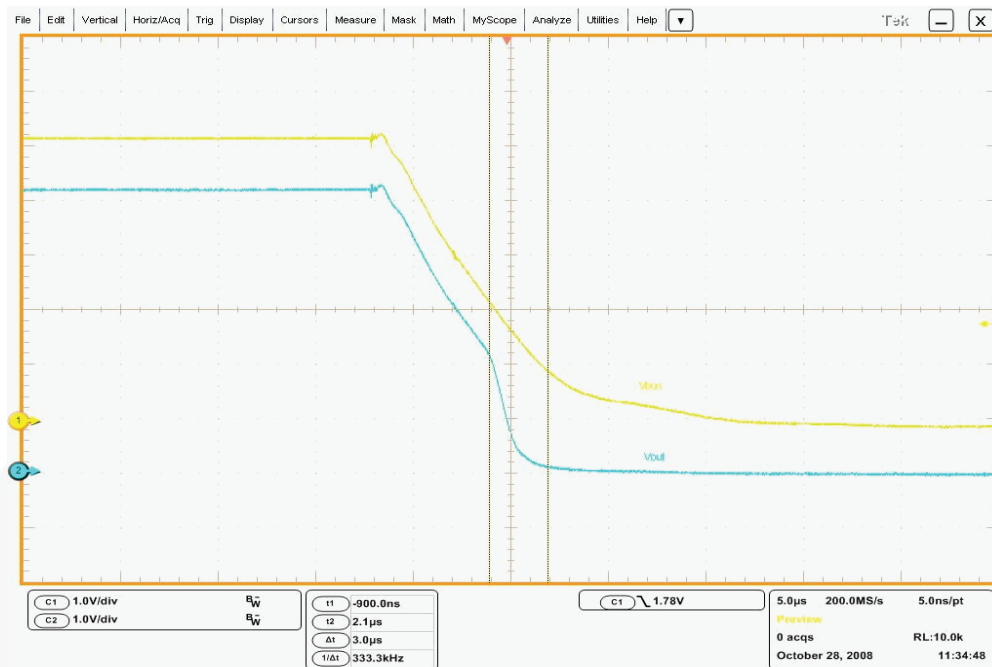


Figure 8. Turn-Off Time

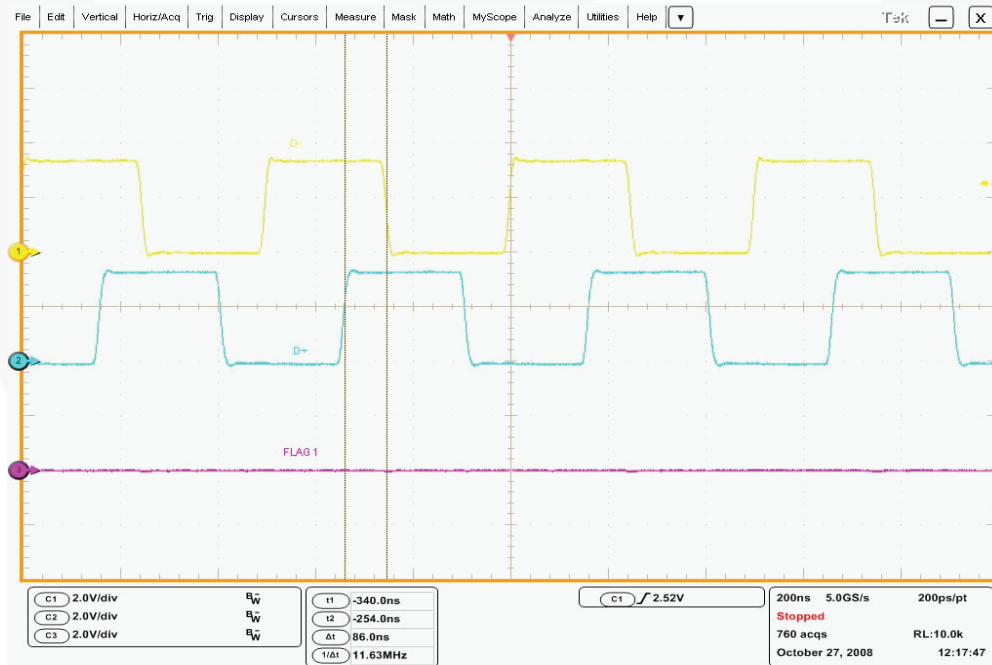


Figure 9. No Fault on Flag 1, Skew=65ns

Typical Performance Characteristics (Continued)

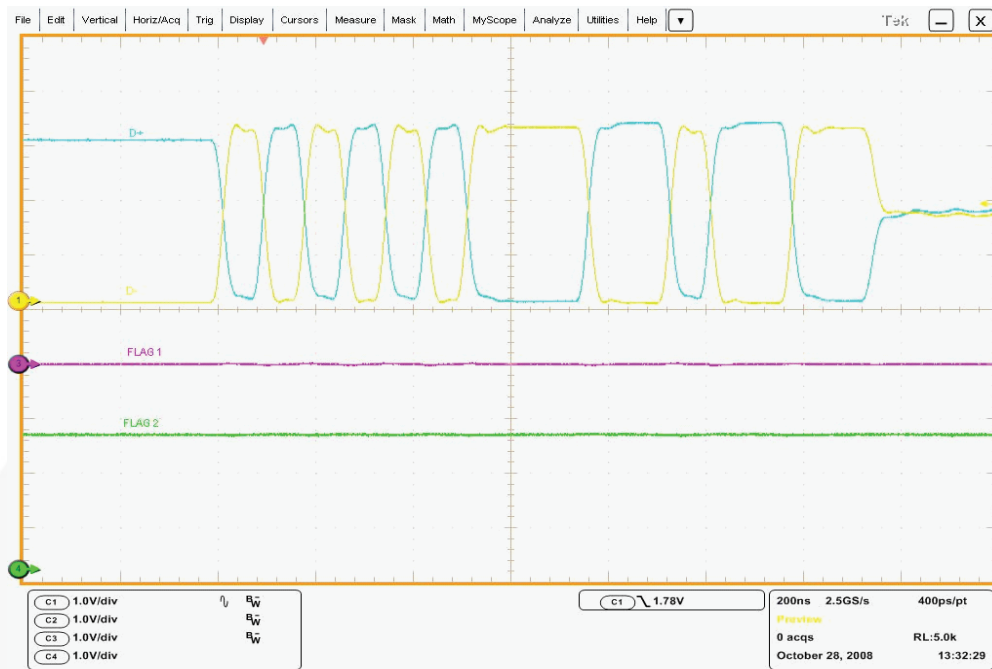


Figure 10. PC Data Running D+/D- (Flag 1 and Flag 2 at Correct Levels)



Figure 11. Standard USB Charger Plug-In

Applications Information

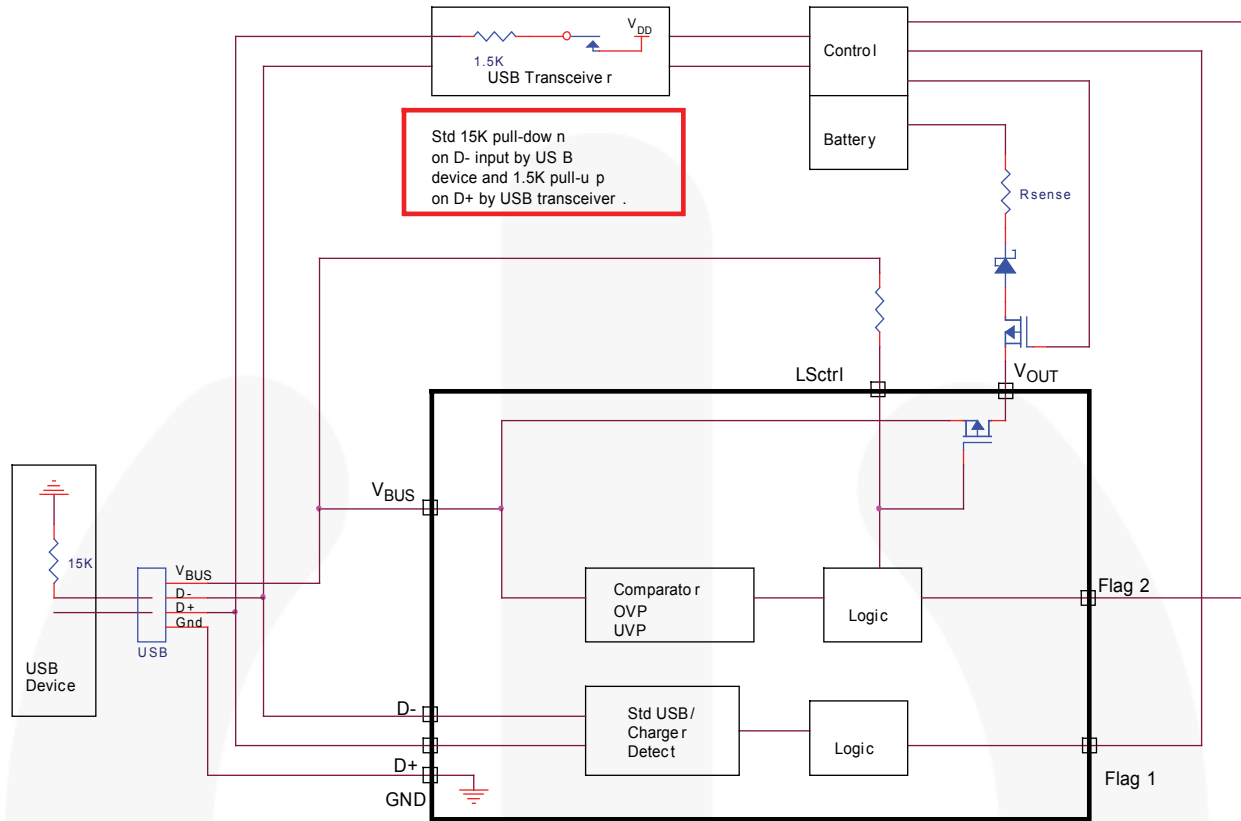


Figure 12. Mobile Phone Battery Charging System with USB Interface

The FAN3989 sets the FLAG1 pin to logic HIGH or LOW as an indicator to the system controller that a standard USB device or a charger is connected to the USB port. The FAN3989 also monitors the V_{BUS} for over- or under-voltage conditions. If V_{BUS} is less than 3.3V or greater than 6.0V, the FLAG2 pin is set LOW and the internal load switch control pin is set HIGH, turning off the PMOS switch.

In a standard USB configuration, there is a switch in the USB transceiver that is always on in full-speed mode. It is on during the transition from full-speed to high-speed mode and turned off after enumeration is

complete. If D+ and D- are shorted when a charger is plugged into the USB port, the USB switch is on and pulled to V_{DD} , which is about 3V, making both D+ and D- HIGH. Flag1 is also set HIGH, indicating that a charging device is connected to the port. If D+ and D- are connected to a standard USB device, the D+ is pulled to V_{DD} and D- is set low (due to the 15KΩ pull-down resistor on the USB device) and flag1 is LOW. If D+ and D- are open (floating), D+ is pulled to V_{DD} and D- floats LOW, which makes flag1 LOW.

Applications Information (Continued)

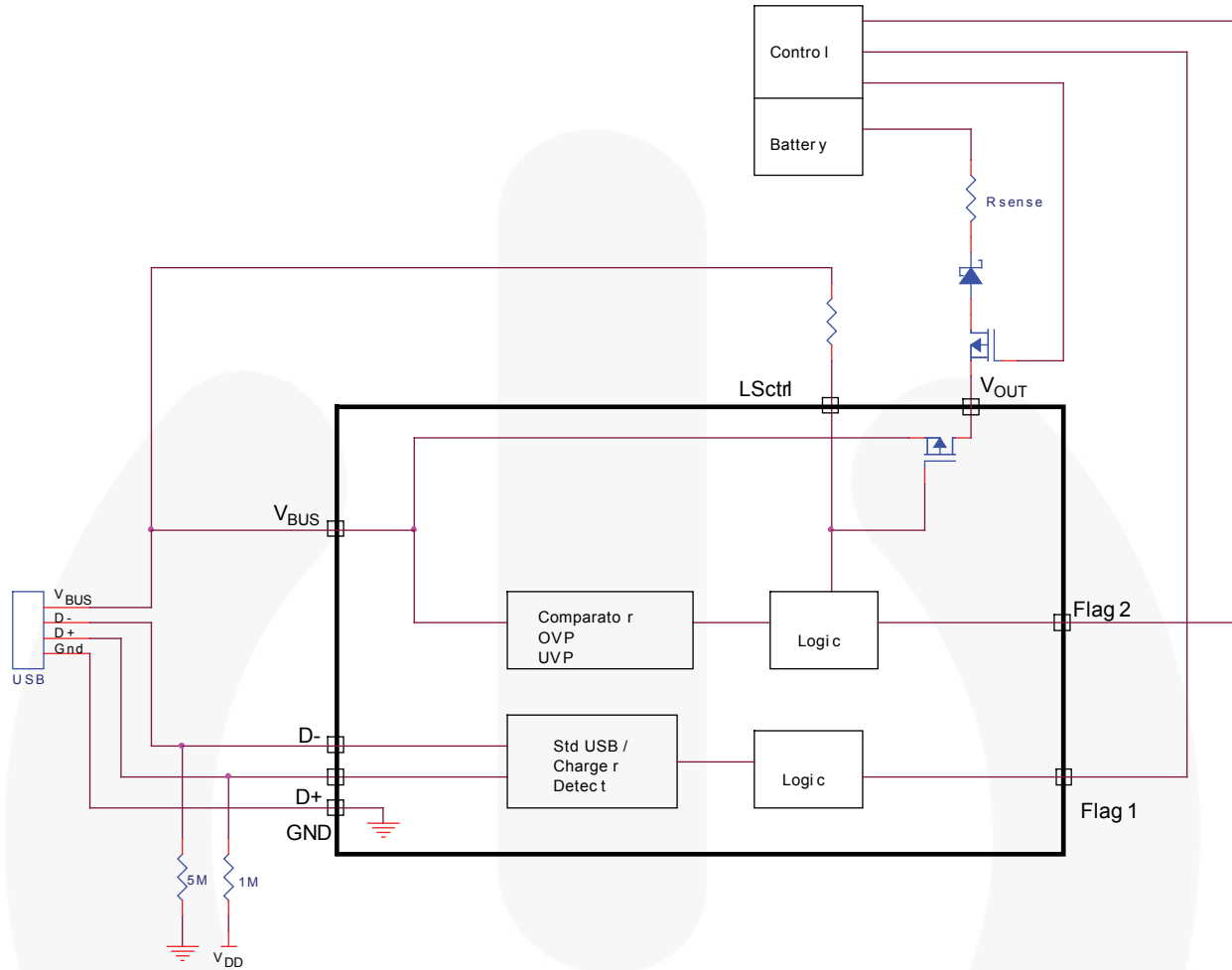


Figure 13. Mobile Phone Battery Charging System without USB Interface

The FAN3989 sets the FLAG1 pin to logic HIGH or LOW as an indicator to the system controller that a standard USB device or a charger is connected to the USB port. The FAN3989 also monitors the V_{BUS} for over- or under-voltage conditions. If V_{BUS} is less than 3.3V or greater than 6.0V, the FLAG2 pin is set LOW and the internal load switch control pin is set HIGH, turning off the PMOS switch.

Where a USB transceiver is not incorporated or there is a switch between the USB port and the FAN3989, external resistors are used to set the correct input logic states on the D+ and D- inputs. A 5MΩ pull-down on the D- line and a 1MΩ pull-up to V_{DD} on the D+ line are recommended. If a charger is plugged into

the USB port (D+ and D- shorted), the voltage divider of 1M and 5M put a voltage of 2.3V on the D+D- inputs and flag1 is HIGH, indicating a charger is connected to port.

If the USB port is connected to a standard USB device, the D+ input is pulled up to V_{DD} and is in parallel with the 1.5KΩ on a USB transceiver with a parallel R value of 1.497KΩ. The D- input is connected to a 15KΩ pull-down by the USB device and in parallel with 5MΩ with a parallel R value of 14.955KΩ. This condition forces flag1 LOW. If D+ and D- are open (floating), D+ is pulled to V_{DD} and D- floats LOW, which forces flag1 LOW.

PCB Layout Guidelines

Please also see Fairchild Semiconductor applications note AN-5067 — PCB Land Pattern Design and Surface Mount Guidelines for MLP Packages

Pad1

This exposed DAP is connected to the internal FET drain and labeled V_{OUT} on the device. The pad should be connected to V_{OUT} pin of the device or left floating. It

should never be connected to the ground, power plane, or Pad2.

Pad2

This exposed DAP is connected to an internal die substrate that is at a ground potential. The pad should be left floating or can be connected to ground plane. This pad should never be connected to Pad1 or the power plane.

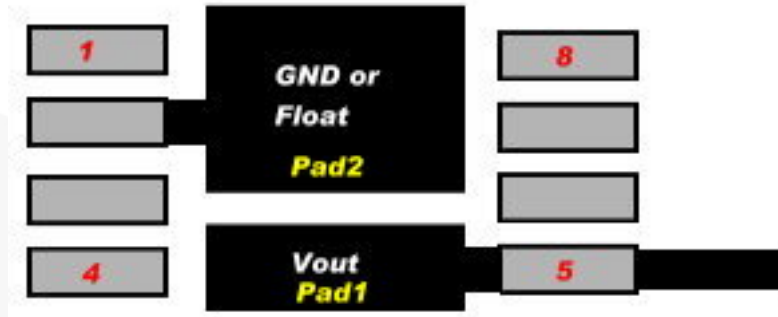


Figure 14. PCD / Pad Layout

Physical Dimensions

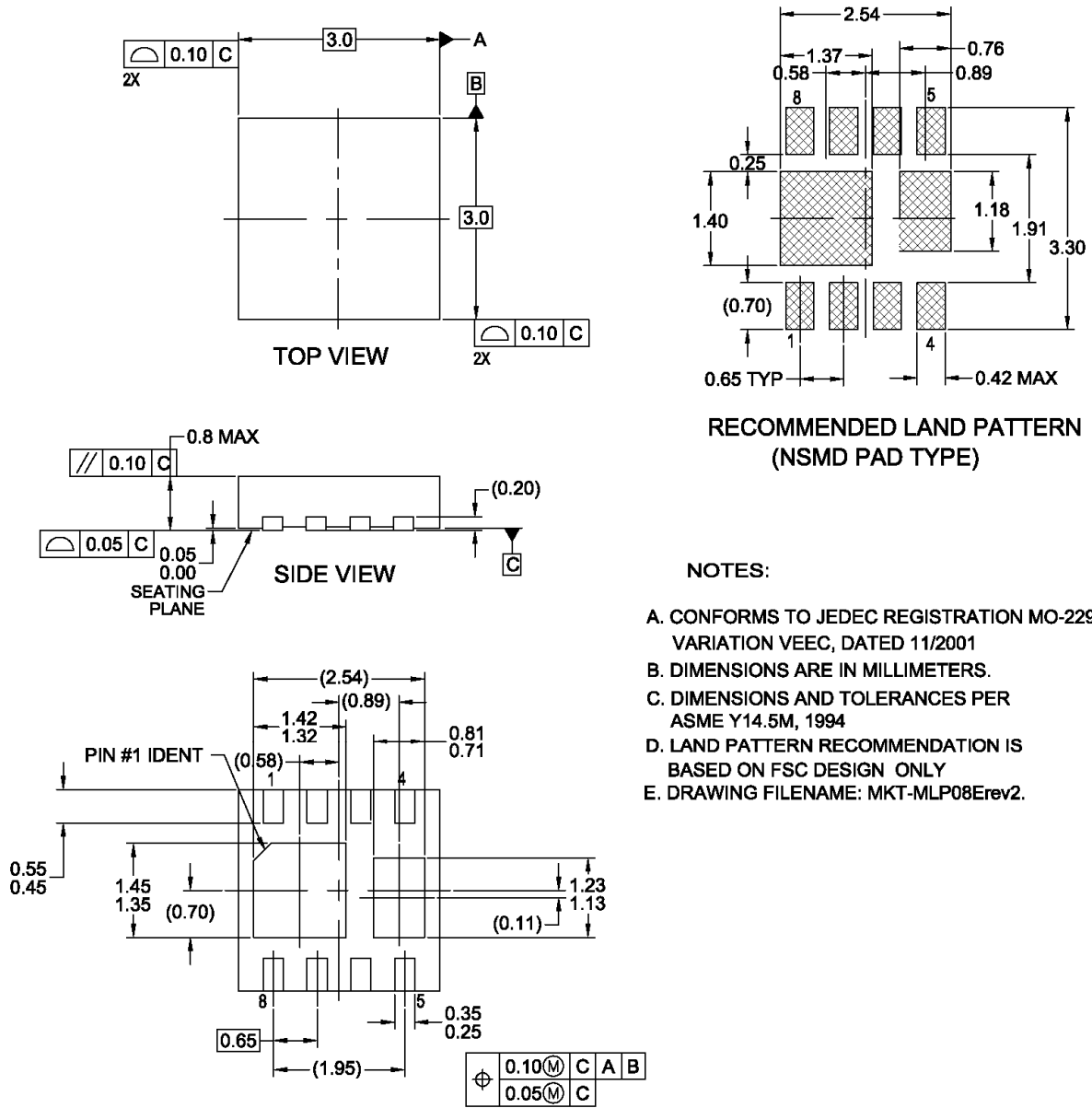


Figure 15. 8-Lead Molded Leadless Package (MLP)





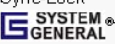
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